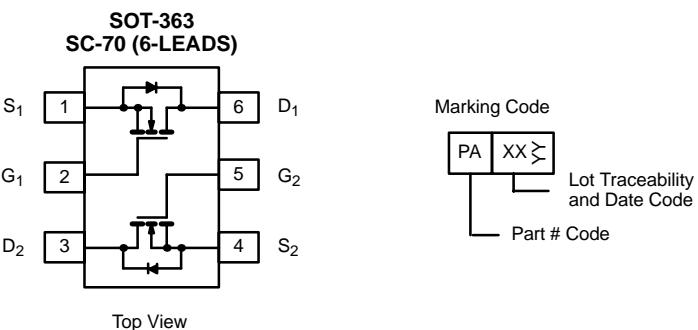


Dual N-Channel 20-V (D-S) MOSFET

**TrenchFET®
Power MOSFETs
2.5-V Rated**

PRODUCT SUMMARY

V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A)
20	0.385 @ $V_{GS} = 4.5$ V	0.70
	0.630 @ $V_{GS} = 2.5$ V	0.54



ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	5 secs	Steady State	Unit
Drain-Source Voltage	V_{DS}	20		V
Gate-Source Voltage	V_{GS}	± 12		
Continuous Drain Current ($T_J = 150^\circ\text{C}$) ^a	I_D	0.70	0.66	A
		0.50	0.48	
Pulsed Drain Current	I_{DM}	1.0		
Continuous Source Current (Diode Conduction) ^a	I_S	0.25	0.23	
Maximum Power Dissipation ^a	P_D	0.30	0.27	W
		0.16	0.14	
Operating Junction and Storage Temperature Range	T_J, T_{stg}	−55 to 150		°C

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^a	R_{thJA}	360	415	°C/W
		400	460	
Maximum Junction-to-Foot (Drain)	R_{thJF}	300	350	

Notes

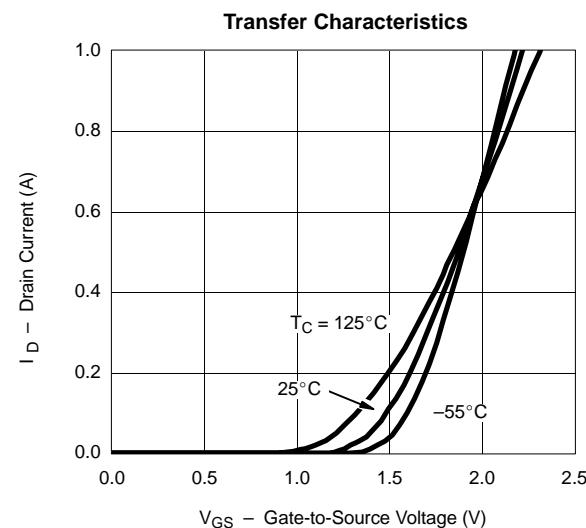
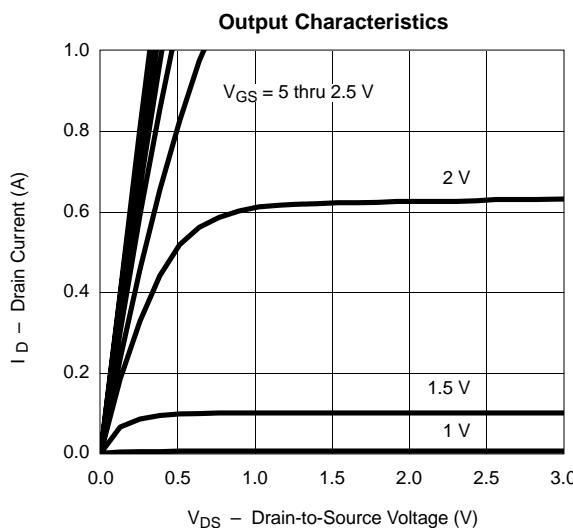
a. Surface Mounted on 1" x 1" FR4 Board.

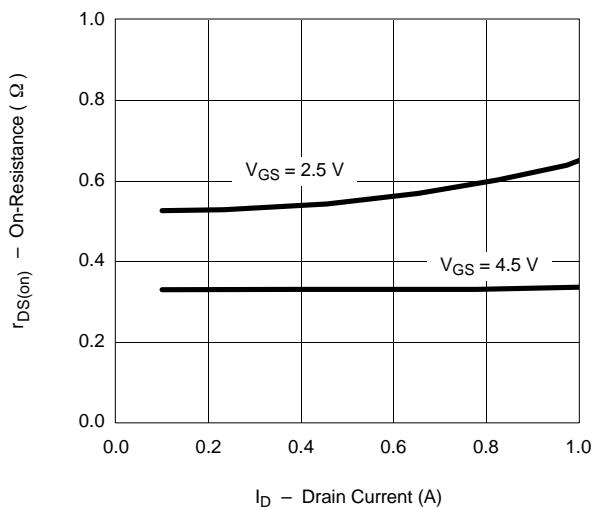
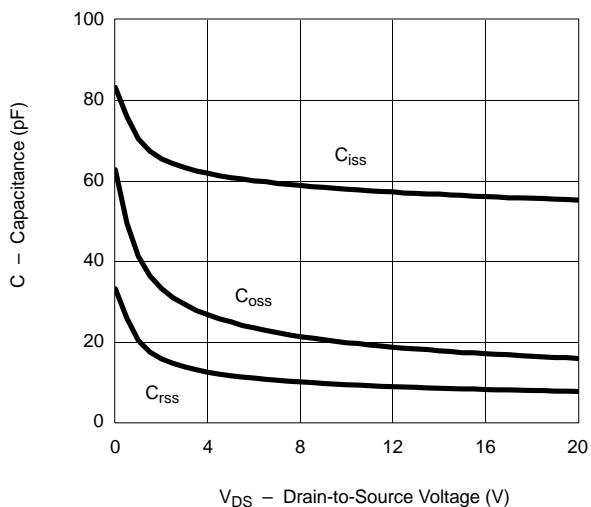
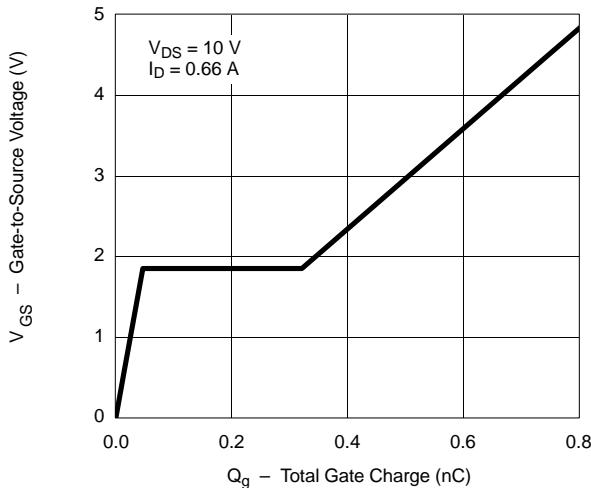
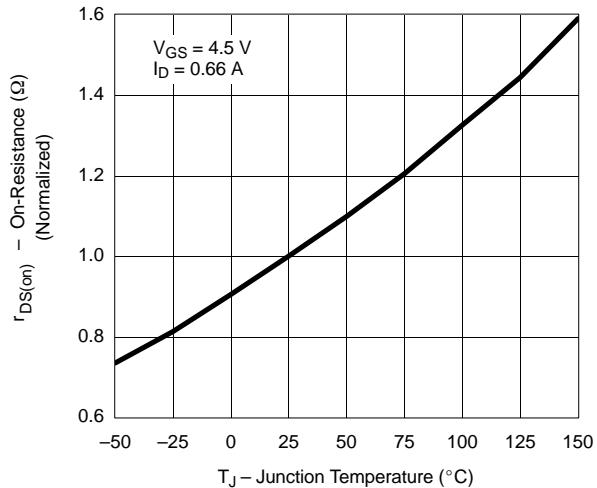
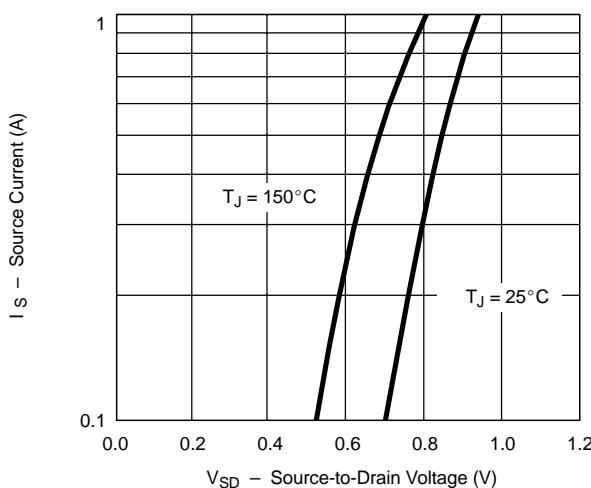
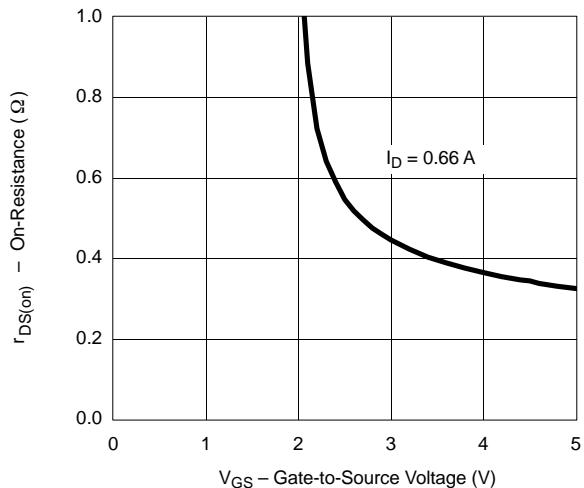
SPECIFICATIONS ($T_J = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	0.6			V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}$		1		μA
		$V_{DS} = 16 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 85^\circ\text{C}$		5		
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} \geq 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	1.0			A
Drain-Source On-State Resistance ^a	$r_{DS(\text{on})}$	$V_{GS} = 4.5 \text{ V}, I_D = 0.66 \text{ A}$		0.320	0.385	Ω
		$V_{GS} = 2.5 \text{ V}, I_D = 0.40 \text{ A}$		0.560	0.630	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 10 \text{ V}, I_D = 0.66 \text{ A}$		1.5		S
Diode Forward Voltage ^a	V_{SD}	$I_S = 0.23 \text{ A}, V_{GS} = 0 \text{ V}$		0.8	1.2	V
Dynamic^b						
Total Gate Charge	Q_g	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 0.66 \text{ A}$		0.8	1.2	nC
Gate-Source Charge	Q_{gs}			0.06		
Gate-Drain Charge	Q_{gd}			0.30		
Turn-On Delay Time	$t_{d(\text{on})}$	$V_{DD} = 10 \text{ V}, R_L = 20 \Omega$ $I_D \approx 0.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_G = 6 \Omega$		10	20	ns
Rise Time	t_r			16	30	
Turn-Off Delay Time	$t_{d(\text{off})}$			10	20	
Fall Time	t_f			10	20	
Source-Drain Reverse Recovery Time	t_{rr}	$I_F = 0.23 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$		20	40	

Notes

- a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2\%$.
- b. Guaranteed by design, not subject to production testing.

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)
On-Resistance vs. Drain Current

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature

Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage


TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)